

# ABSTRACT OF THE DISCLOSURE

A method for producing a semiconductor-molding tablet, which can reduce formation of voids in the package due to increased density of the tablet. The method  
5 comprises a step of kneading an epoxy resin composition comprising components (A) an epoxy resin, (B) a phenol resin, and (C) an inorganic filler as essential components, a step of roll-molding the resulting kneaded composition into a sheet shape having a sheet density ratio  
10 of 98% or more, a step of pulverizing the resulting sheet-shaped compact, and a step of forming the pulverized material into a tablet shape having a tablet density ratio of 94% or more and less than 98%.